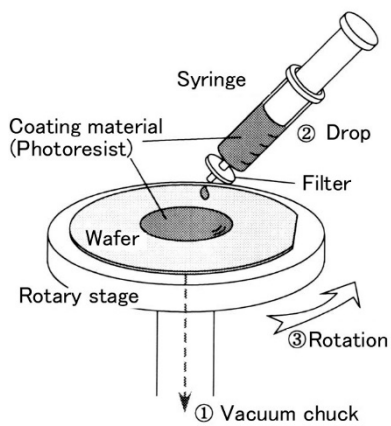
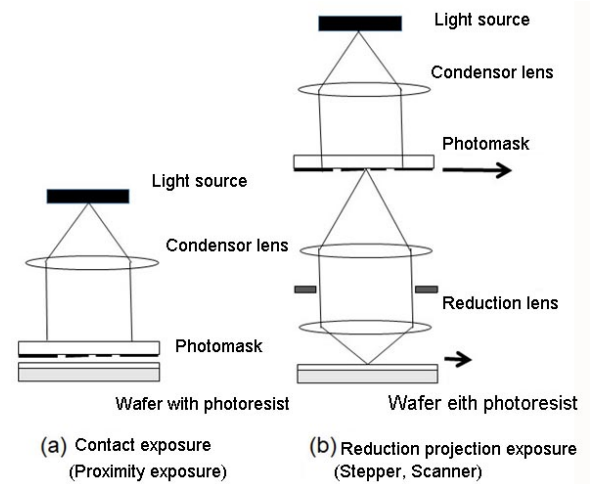


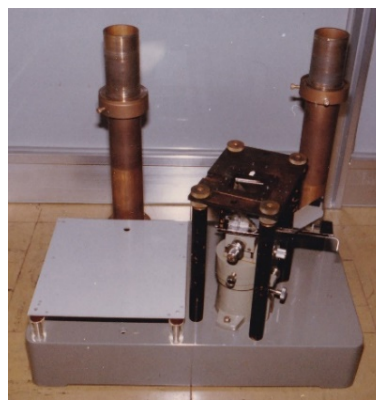
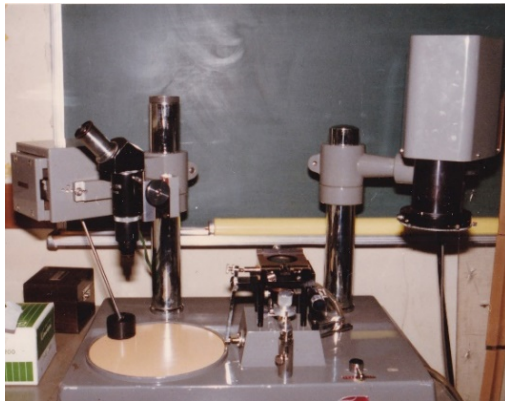
2 Photoresist coating, patterning and etching



Spin coater (exhibited)

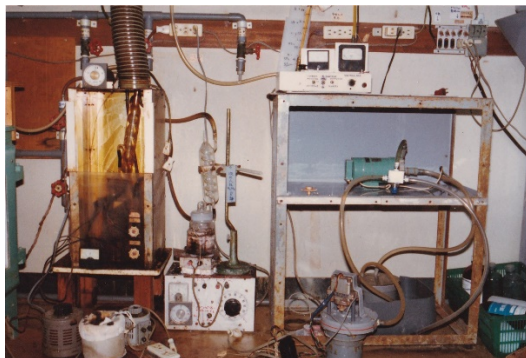


Principles of exposure systems

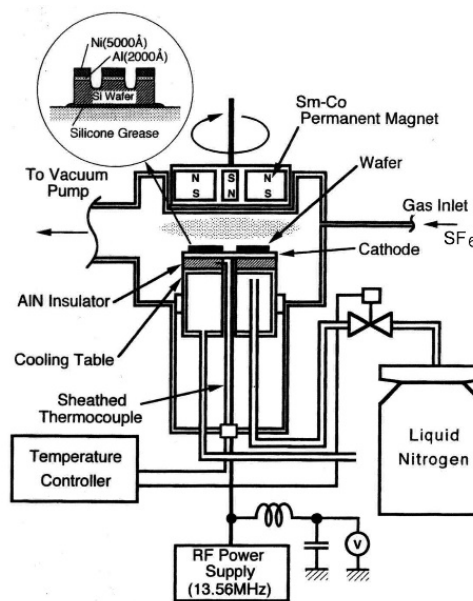


Contact exposure system and modified double side system

Double side exposure system (exhibited)



Wet etching (Si_3N_4)



Dry etching (Si reactive ion etching (DRIE))

